

**Features**

- Low profile package
- Ideal for automated placement
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC



SMA (DO-214AC)

Mechanical Date

- **Case:** JEDEC DO-214AC molded plastic
- **Terminals:** Solder plated, solderable per
JESD22-B102D
- **Polarity:** Laser band denotes cathode end

Major Ratings and Characteristics

$I_{F(AV)}$	3.0A
V_{RRM}	20 V to 60 V
I_{FSM}	100A
V_F	0.40V, 0.65V
$T_j \text{ max.}$	125 °C

Maximum Ratings & Thermal Characteristics(T_A = 25 °C unless otherwise noted)

Items	Symbol	SS32LA	SS33LA	SS34LA	SS36LA	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	60	V
Maximum RMS voltage	V_{RMS}	14	21	28	42	V
Maximum DC blocking voltage	V_{DC}	20	30	40	60	V
Maximum average forward rectified current	$I_{F(AV)}$	3				A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	100				A
Voltage rate of change (rated V _R)	dv/dt	10000				V/μs
Thermal resistance from junction to lead ⁽¹⁾	$R_{θJL}$	35				°C/W
Operating junction and storage temperature range	T_J, T_{STG}	-65 to +125				°C

Note 1: Mounted on P.C.B. with 0.2 x 0.2" (5.0 x 5.0mm) copper pad areas.

Electrical Characteristics (T_A = 25 °C unless otherwise noted)

Items	Test conditions	Symbol	SS32~34	SS36	UNIT
Instantaneous forward voltage	$I_F=3.0A^{(2)}$	V_F	0.40	0.65	V
Reverse current	$V_R=V_{DC}$	I_R	1.0		mA
			20		

Note 2: Pulse test:300μs pulse width,1% duty cycle.

Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

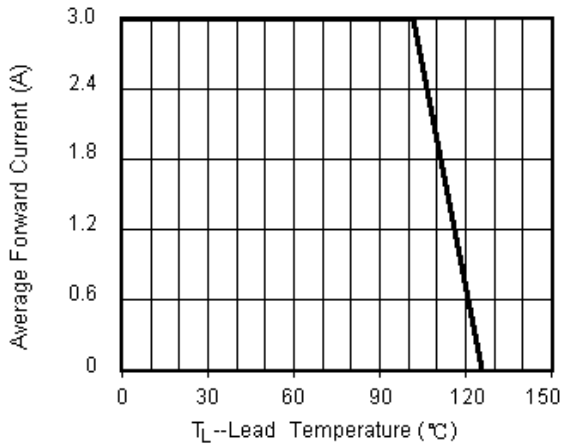


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

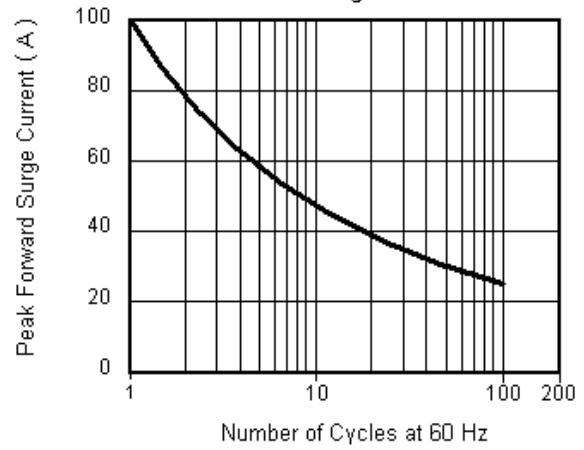


Fig.3 Typical Instantaneous Forward Characteristics

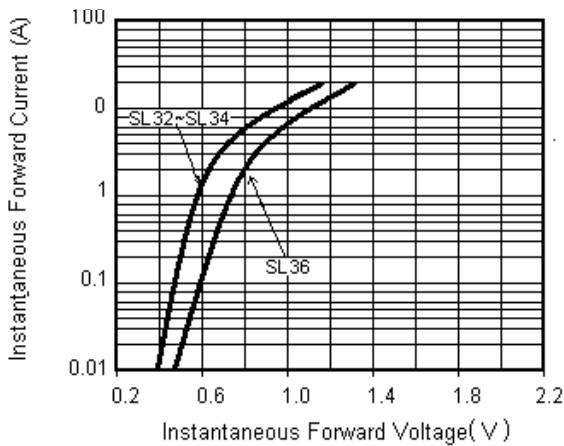
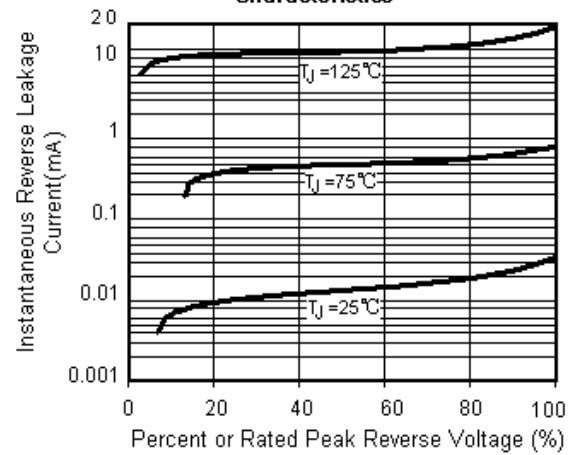
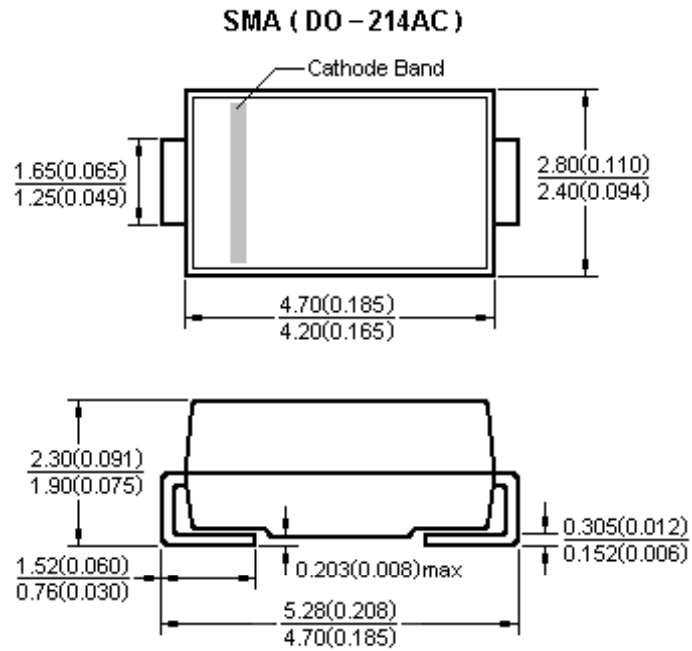


Fig.4 Typical Reverse Leakage Characteristics



Package Outline



Dimensions in millimeters and (inches)